## **DECLARATION AND POWER OF ATTORNEY FOR PATENT APPLICATION**

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled A Thermoformable Lamination Containing A Flexible Polyamide Coextrusion, the specification of which:

<u>X</u>	is attached hereto.	
	was filed on	as
	Application Serial No.	
	and was amended on	_ (if applicable).

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, Section 1.56(a).

I hereby claim foreign priority benefits under Title 35, United States Code, Section 119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the

application on which priority is claimed:

PRIOR FOREIGN APPLICATION(S)						
<u>Country</u>	<u>Number</u>	Date Filed	Priority (Yes	<u>Claimed</u> <u>No</u>		
			_			
	<del> </del>					
I hereby claim the b	enefit under Title 35, Uni	ited States Code Secti	on 120 of any l	United States		
application(s) listed	below and, insofar as the su	ibject matter of each of	the claims of th	is application		
is not disclosed in the	e prior United States applie	cation in the manner pr	ovided by the fi	rst paragraph		
of Title 35, United St	ates Code, Section 112, I ac	knowledge the duty to	disclose materia	linformation		
as defined in Title 3	7, Code of Federal Regula	ations, Section 1.56(a)	which occurred	between the		
filing date of the p	rior application and the	national or PCT inte	rnational filing	date of this		
application.						
Application Serial	No. <u>F</u>	iling Date	<u>S</u> 1	atus		

And I hereby appoint Dennis M. McWilliams, Registration No. 25,195, Thomas E. Smith, Registration No. 18,243, James R. Sweeney, Registration No. 18,721, William M. Lee, Jr., Registration No. 26,935, Glenn W. Ohlson, Registration No. 28,455, David C. Brezina, Registration No. 34,128, Jeffrey R. Gray, Registration No. 33,391, Timothy J. Engling, Registration No. 39,970, Gerald S. Geren, Registration No. 24,528, Peter J. Shakula, Registration No. 40,808, Robert F.I. Conte, Registration No. 20,354, Gregory Beggs, Registration No. 19,286, John W. Hayes, Registration No. 33,900, and Howard B. Rockman, Registration No. 22,190 to prosecute this

application and to transact all business in the Patent and Trademark Office connected herewith. It is requested that all communications be directed to Lee, Mann, Smith, McWilliams, Sweeney & Ohlson, P.O. Box 2786, Chicago, Illinois 60690-2786, telephone number (312) 368-1300.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full name of sole or first inventor: <u>Andrea Maylene Carlson</u>						
Signature Date						
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Country of Citizenship:						
Post Office and Residence Address: <u>3740 Summerset Way, Oshkosh, Wisconsin, 54901</u>						
Full name of joint inventor: Gregory Robert Pockat						
Signature Date						
Country of Residence: <u>United States</u>						
Country of Citizenship:						

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